

HEAT CURABLE COMPOSITION

ABSTRACT

There is provided a resin composition that can allow a drying step after impregnation coating of a prepreg and lamination pressing to be performed at low temperatures in a short time and, at the same time, can maintain storage stability of the prepreg. The resin composition according to the present invention comprises (A) an imidazole compound represented by formula (I), (B) an epoxy compound, and (C1) a cyanate compound or (C2) a BT resin. In the formula, R^1 and R^2 each independently represent an alkyl group having 3 to 18 carbon atoms, an alkenyl group having 3 to 18 carbon atoms, an alkoxy group having 3 to 18 carbon atoms, or a substituted or unsubstituted aromatic substituent having 6 to 14 carbon atoms; and R^3 represents hydrogen, an alkyl group having 1 to 18 carbon atoms, an alkenyl group having 2 to 18 carbon atoms, an alkoxy group having 1 to 18 carbon atoms, a substituted or unsubstituted aromatic substituent having 6 to 14 carbon atoms, or a halogen group.